LNJ953W8CRA

Hight Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I _F 15		mA	
Pulse forward current *	I _{FP} 70		mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

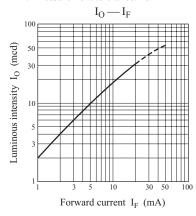
• Blue

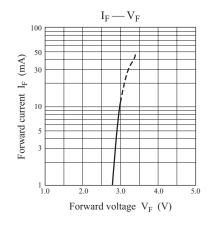
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

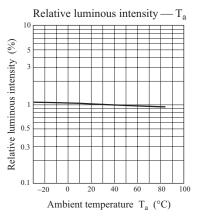
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	7.0	10.0	34.7	mcd
Reverse current	I_R	$V_R = 5 V$			100	μА
Forward voltage	V _F	$I_F = 5 \text{ mA}$		2.9	3.2	V
Peak emission wavelength	λ_{P}	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 5 \text{ mA}$	462	470	478	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

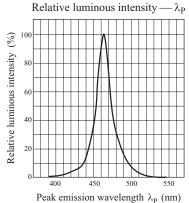
Note) *1: Measurement tolerance: $\pm 20\%$

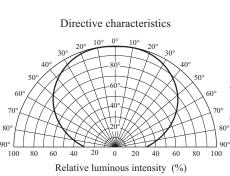
^{*2:} Measurement tolerance: ±3 nm

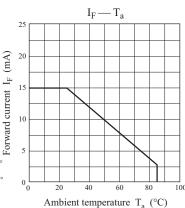






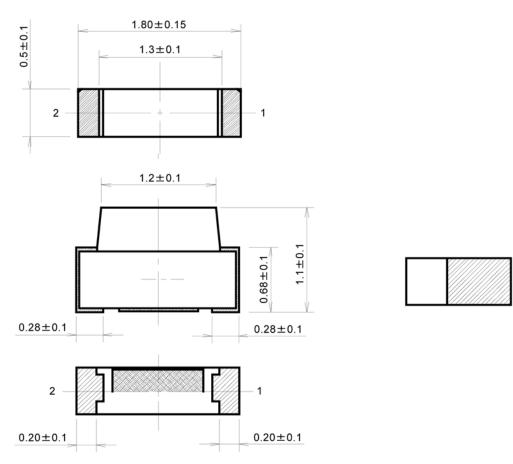






■ Package (Unit: mm)

KLTFSN2K5300



- Pin name
 - 1: Anode
 - 2: Cathode

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